



BSI Standards Publication

Device embedding assembly technology

Part 2-603: Guideline for stacked electronic module — Test method of intra-module electrical connectivity

National foreword

This British Standard is the UK implementation of EN IEC 62878-2-603:2025. It is identical to IEC 62878-2-603:2025.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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